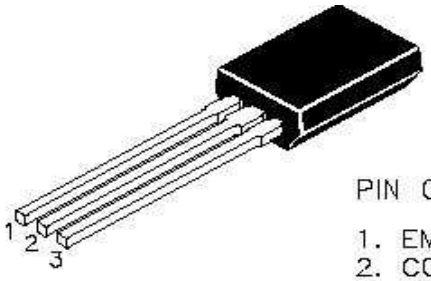
NPN SILICON PLANAR EPITAXIAL TRANSISTOR

CSCL2482

TO-92L
Plastic Package



PIN CONFIGURATION:–

1. EMITTER
2. COLLECTOR
3. BASE

High Voltage Switching and Amplifier Applications
CTV Horizontal Driver and Chroma Output Applications

ABSOLUTE MAXIMUM RATINGS (T_a=25ºC unless specified otherwise)

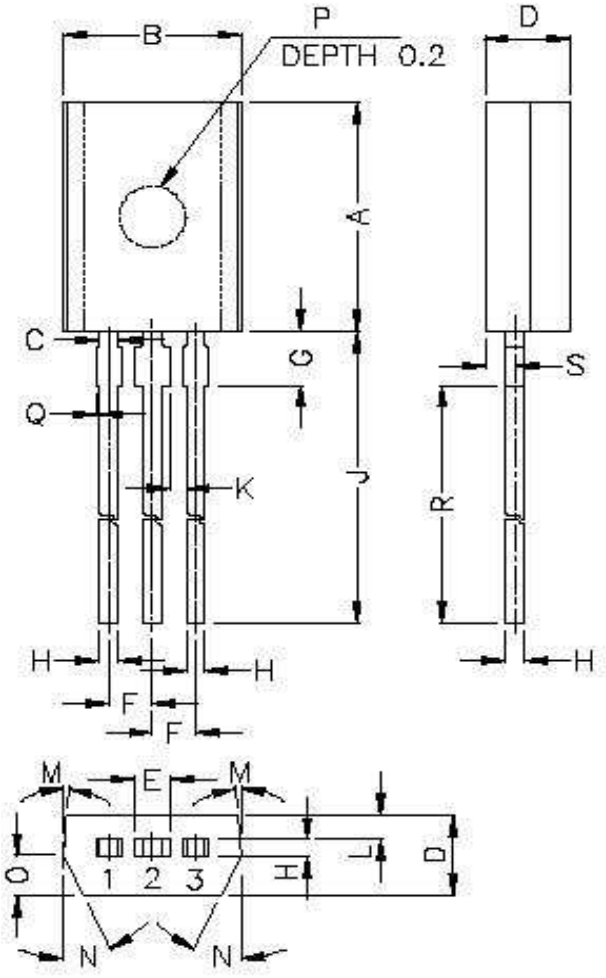
DESCRIPTION	SYMBOL	VALUE	UNITS
Collector Emitter Voltage	V_{CEO}	300	V
Collector Base Voltage	V_{CBO}	300	V
Emitter Base Voltage	V_{EBO}	7	V
Collector Current	I_C	100	mA
Base Current	I_B	50	mA
Collector Power Dissipation	P_C	900	mW
Storage Temperature	T_{stg}	- 55 to +150	ºC
Junction Temperature	T_j	150	ºC

ABSOLUTE MAXIMUM RATINGS(T_a=25ºC unless specified otherwise)

DESCRIPTION	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNITS
Collector Cut Off Current	I_{CBO}	V_{CB}=240V, I_E = 0			1.0	µA
Emitter Cut Off Current	I_{EBO}	V_{EB}=7V, I_C = 0			1.0	µA
DC Current Gain	h_{FE}	V_{CE}=10V, I_C=4mA V_{CE}=10V, I_C=20mA	20 30		 150	
Collector Emitter Saturation Voltage	$V_{CE\ (sat)}$	I_C=10mA, I_B=1mA			1.0	V
Base Emitter Saturation Voltage	$V_{BE\ (sat)}$	I_C=10mA, I_B=1mA			1.0	V
Transition Frequency	f_T	V_{CE}=10V, I_C=20mA	50			MHz
Collector Output Capacitance	C_{Ob}	V_{CB}=20V, I_E=0, f=1MHz		3.0		pF

CSCL2482Rev250506E

PACKAGE TO–92L



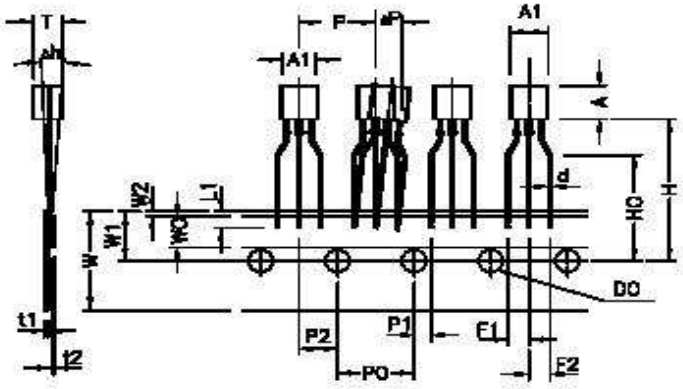
DIMENSIONS			
REF DIM	MIN	NOM	MAX
A	–	–	7.20
B	–	–	5.20
C	–	–	0.60
D	–	–	2.50
E	–	–	1.15
F	–	1.27	–
G	–	–	1.70
H	–	–	0.55
J	13.50	–	14.50
K	0.35	–	–
L	0.65	–	0.85
M	–	4°	–
N	–	25°	–
O	–	1.25	–
P	–	ø1.50	–
Q	–	–	0.10
R	12.00	–	13.00
S	–	1.00	–

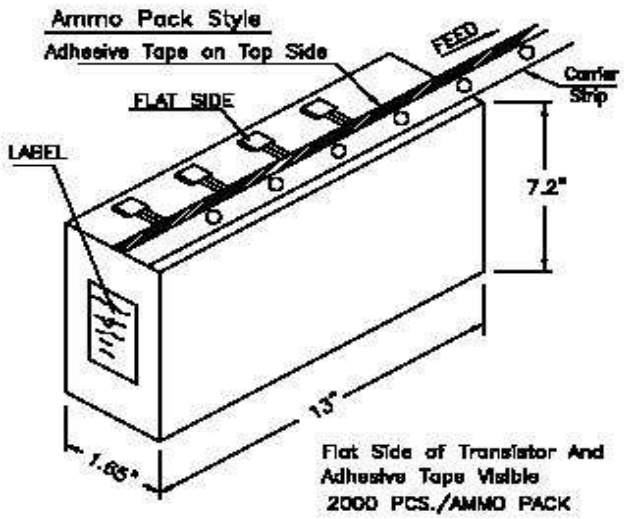
ALL DIMENSIONS ARE IN M.M.

PIN CONFIGURATION:–

1. EMITTER
2. COLLECTOR
3. BASE

TO−92L TRANSISTOR ON TAPE AND AMMO PACK





ITEM	SYMBOL	VALUE & TOLERANCE
BODY WIDTH	A1	4.9 ±0.2
BODY HEIGHT	A	8.0 ±0.2
BODY THICKNESS	T	3.9 ±0.2
LEAD WIRE DIAMETER	d	0.45 ±0.05
PITCH OF COMPONENT	P	12.7 ±0.3
FEED HOLE PITCH	P0	12.7 ±0.2
HOLE CENTER TO COMPONENT CENTER	P2	6.35 ±0.3
LEAD TO LEAD DISTANCE	F1,F2	2.5 ±0.3
COMPONENT ALIGNMENT,F−R	Δh	0 ±1.0
TYPE WIDTH	W	18.0 +1.0,−0.5
HOLE DOWN TAPE WIDTH	W0	6.0 ±0.5
HOLE POSITION	W1	9.0 ±0.5
HOLE DOWN TAPE POSITION	W2	1.0 MAX.
HEIGHT OF COMPONENT FROM TAPE CENTER	H	19.0 +2.0,−0
LEAD WIRE CLINCH HEIGHT	H0	16.0 ±0.5
LEAD WIRE (TAPE PORTION)	L1	2.5 MIN
FEED HOLE DIAMETER	D0	4.0 ±0.2
TAPED LEAD THICKNESS	t1	0.4 ±0.05
CARRIER TAPE THICKNESS	t2	0.2 ±0.05
POSITION OF HOLE	P1	3.85 ±0.3
COMPONENT ALIGNMENT	ΔP	0 ±1.0

NOTES:−

1. MAXIMUM ALIGNMENT DEVIATION BETWEEN LEADS NOT TO BE GREATER THAN 0.2 mm
2. MAXIMUM NON−CUMULATIVE VARIATION BETWEEN TAPE FEED HOLES SHALL NOT EXCEED 1 mm IN 20 PITCHES.
3. HOLDDOWN TAPE NOT TO EXCEED BEYOND THE EDGE(S) OF CARRIER TAPE AND THERE SHALL BE NO EXPOSURE OF ADHESIVE.
4. NO MORE THAN 3 CONSECUTIVE MISSING COMPONENTS IS PERMITTED.
5. A TAPE TRAILER, HAVING AT LEAST THREE FEED HOLES IS REQUIRED AFTER THE LAST COMPONENT.
6. SPLICES SHALL NOT INTERFERE WITH THE SPROCKET FEED HOLES.

Component Disposal Instructions

1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.

2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

Disclaimer

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